

MMBT2907AM3T5G

PNP General Purpose Transistor

The MMBT2907AM3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- Reduces Board Space
- This is a Halide-Free Device
- This is a Pb-Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V_{CEO}	–60	Vdc
Collector–Base Voltage	V_{CBO}	–60	Vdc
Emitter–Base Voltage	V_{EBO}	–5.0	Vdc
Collector Current – Continuous	I_C	–600	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	265 2.1	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	470	$^\circ\text{C/W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	640 5.1	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	195	$^\circ\text{C/W}$
Junction and Storage Temperature	T_J, T_{stg}	–55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

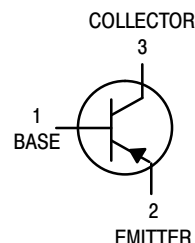
1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

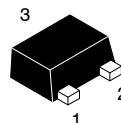


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MARKING DIAGRAM



SOT-723
CASE 631AA
STYLE 1



AC = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
MMBT2907AM3T5G	SOT-723 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage (Note 3) (I _C = –10 mA _{dc} , I _B = 0)	V _{(BR)CEO}	–60	–	V _{dc}
Collector–Base Breakdown Voltage (I _C = –10 μA _{dc} , I _E = 0)	V _{(BR)CBO}	–60	–	V _{dc}
Emitter–Base Breakdown Voltage (I _E = –10 μA _{dc} , I _C = 0)	V _{(BR)EBO}	–5.0	–	V _{dc}
Collector Cutoff Current (V _{CE} = –30 V _{dc} , V _{EB(off)} = –0.5 V _{dc})	I _{CEX}	–	–50	nA _{dc}
Collector Cutoff Current (V _{CB} = –50 V _{dc} , I _E = 0) (V _{CB} = –50 V _{dc} , I _E = 0, T _A = 125°C)	I _{CBO}	–	–0.010 –10	μA _{dc}
Base Cutoff Current (V _{CE} = –30 V _{dc} , V _{EB(off)} = –0.5 V _{dc})	I _{BL}	–	–50	nA _{dc}

ON CHARACTERISTICS

DC Current Gain (I _C = –0.1 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –1.0 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –10 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –150 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –500 mA _{dc} , V _{CE} = –10 V _{dc}) (Note 3)	h _{FE}	75 100 100 100 50	– – – 300 –	–
Collector–Emitter Saturation Voltage (Note 3) (I _C = –150 mA _{dc} , I _B = –15 mA _{dc}) (Note 3) (I _C = –500 mA _{dc} , I _B = –50 mA _{dc})	V _{CE(sat)}	– –	–0.4 –1.6	V _{dc}
Base–Emitter Saturation Voltage (Note 3) (I _C = –150 mA _{dc} , I _B = –15 mA _{dc}) (I _C = –500 mA _{dc} , I _B = –50 mA _{dc})	V _{BE(sat)}	– –	–1.3 –2.6	V _{dc}

SMALL–SIGNAL CHARACTERISTICS

Current–Gain – Bandwidth Product (Notes 3, 4) (I _C = –50 mA _{dc} , V _{CE} = –20 V _{dc} , f = 100 MHz)	f _T	200	–	MHz
Output Capacitance (V _{CB} = –10 V _{dc} , I _E = 0, f = 1.0 MHz)	C _{obo}	–	8.0	pF
Input Capacitance (V _{EB} = –2.0 V _{dc} , I _C = 0, f = 1.0 MHz)	C _{ibo}	–	30	pF

SWITCHING CHARACTERISTICS

Turn–On Time	(V _{CC} = –30 V _{dc} , I _C = –150 mA _{dc} , I _{B1} = –15 mA _{dc})	t _{on}	–	45	ns
Delay Time		t _d	–	10	
Rise Time		t _r	–	40	
Turn–Off Time	(V _{CC} = –6.0 V _{dc} , I _C = –150 mA _{dc} , I _{B1} = I _{B2} = –15 mA _{dc})	t _{off}	–	100	
Storage Time		t _s	–	80	
Fall Time		t _f	–	30	

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

4. f_T is defined as the frequency at which |h_{fe}| extrapolates to unity.

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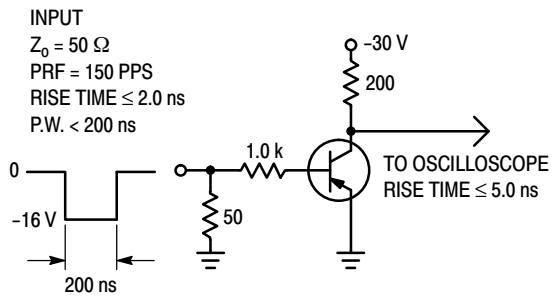


Figure 1. Delay and Rise Time Test Circuit

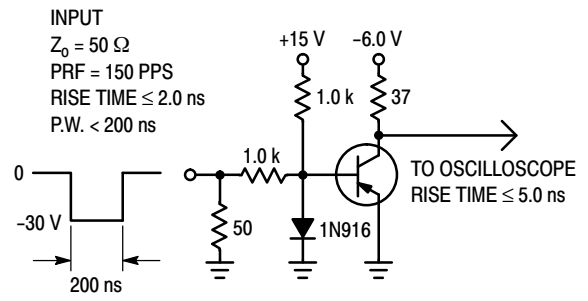


Figure 2. Storage and Fall Time Test Circuit

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TYPICAL CHARACTERISTICS

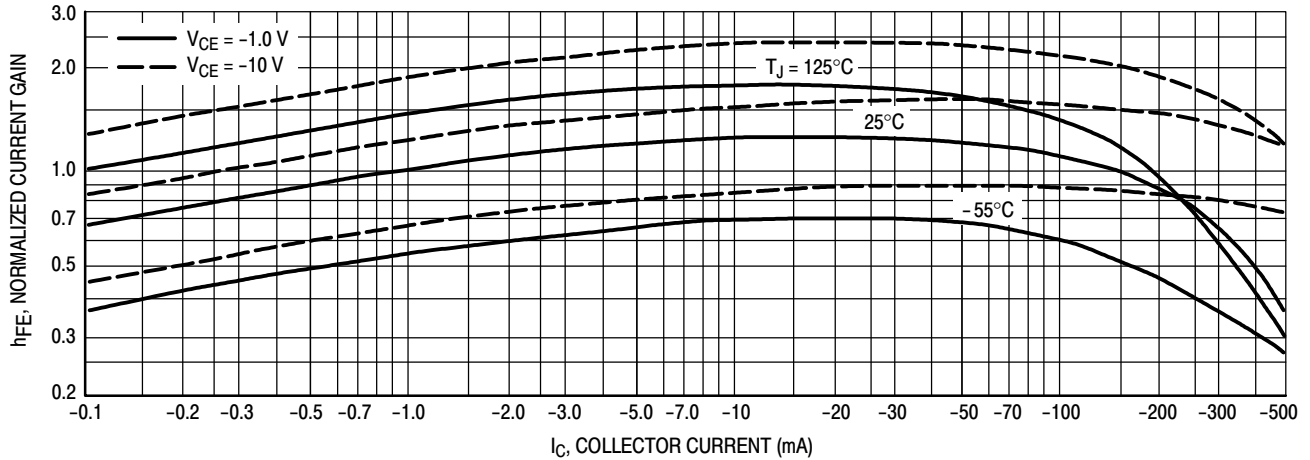


Figure 3. DC Current Gain

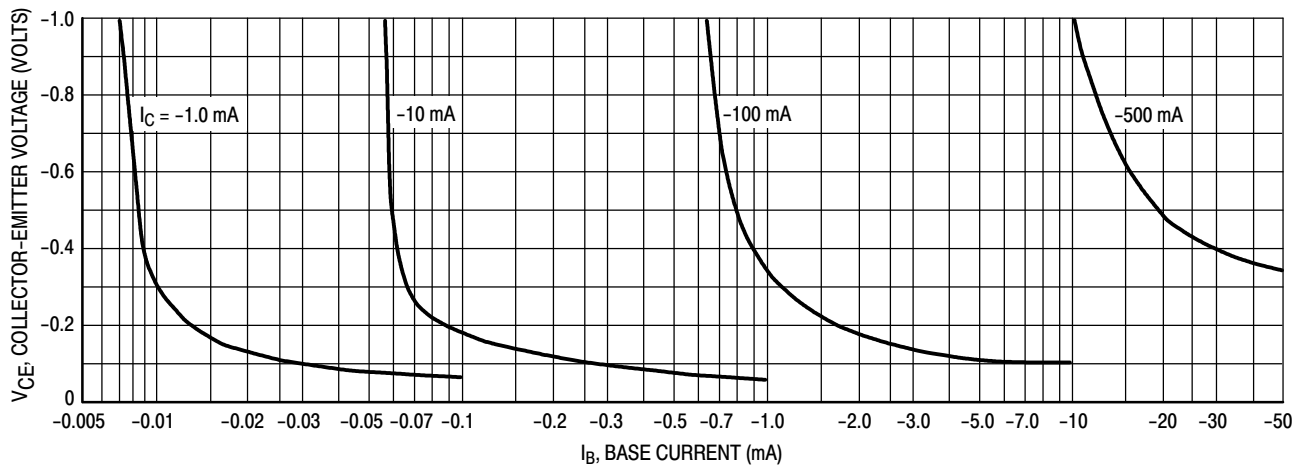


Figure 4. Collector Saturation Region

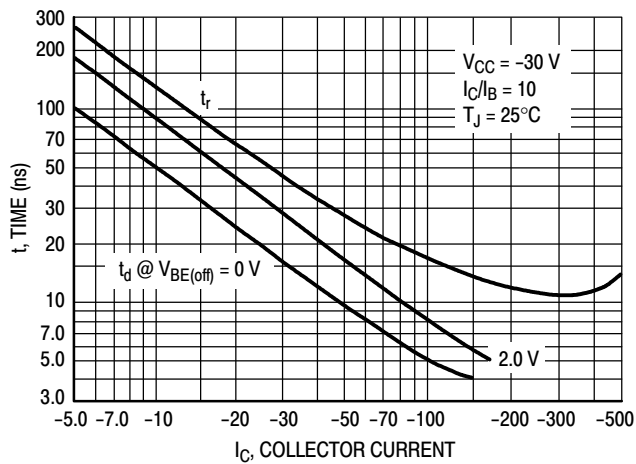


Figure 5. Turn-On Time

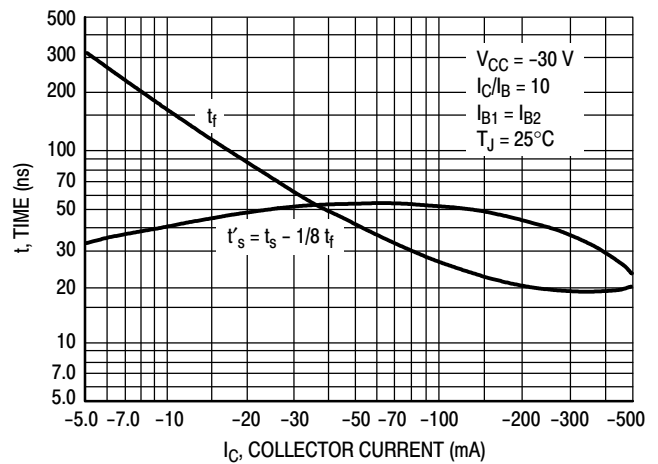


Figure 6. Turn-Off Time

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TYPICAL SMALL-SIGNAL Characteristics NOISE FIGURE

$V_{CE} = 10 \text{ Vdc}$, $T_A = 25^\circ\text{C}$

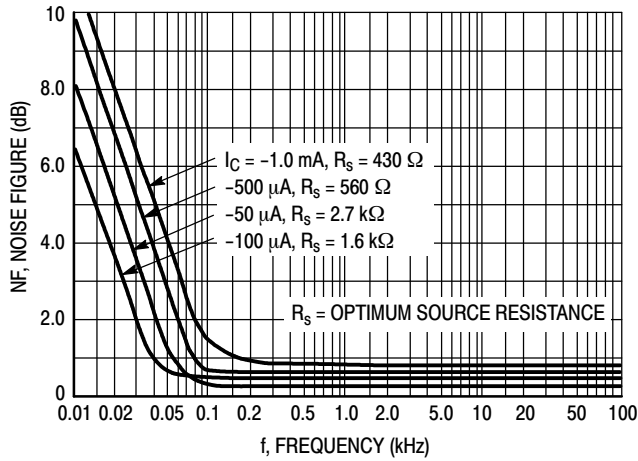


Figure 7. Frequency Effects

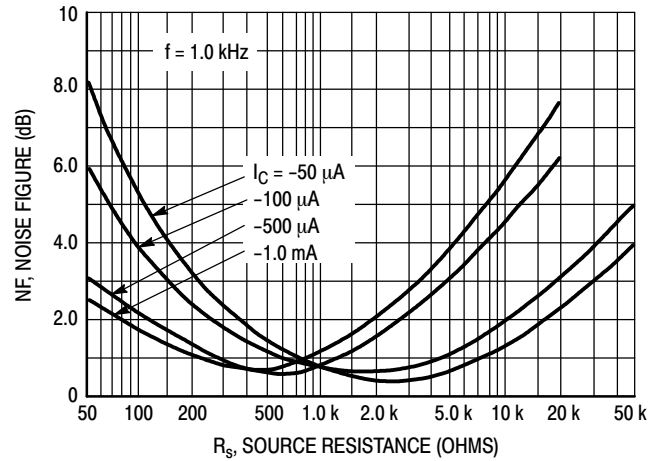


Figure 8. Source Resistance Effects

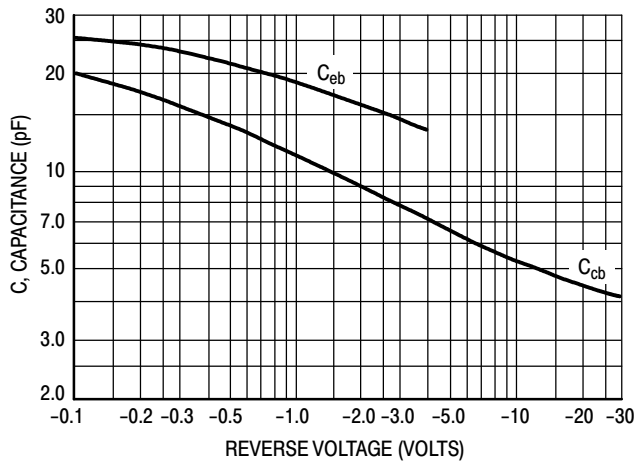


Figure 9. Capacitances

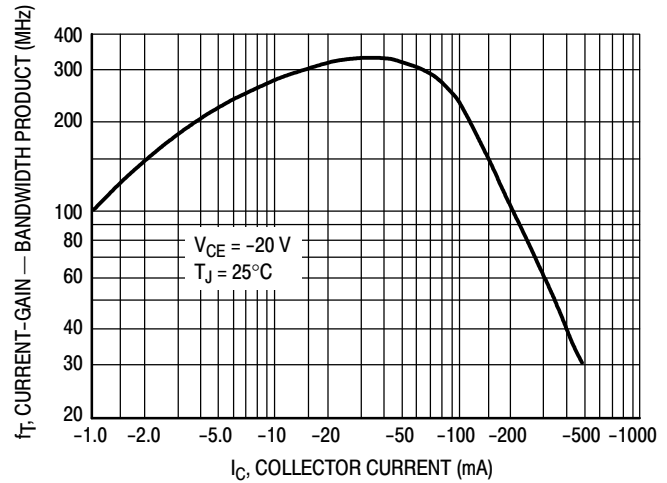


Figure 10. Current-Gain - Bandwidth Product

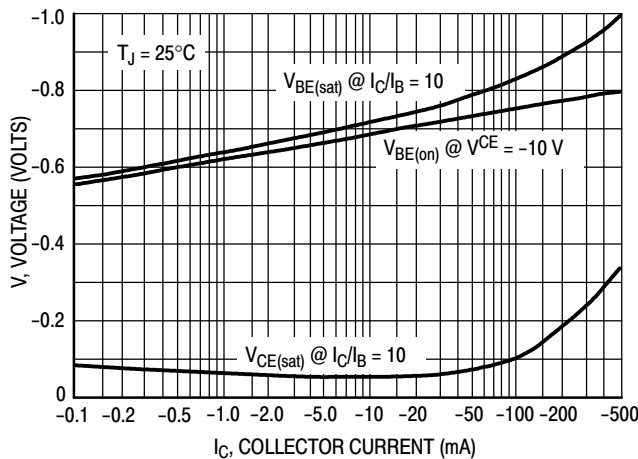


Figure 11. "On" Voltage

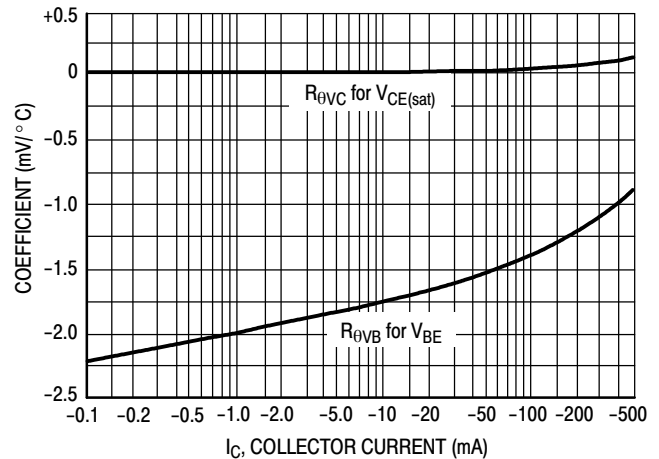
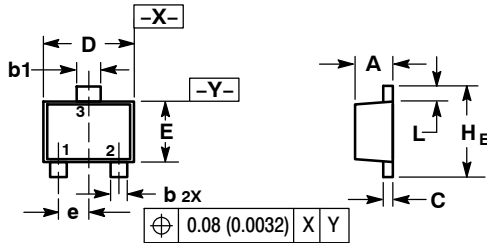


Figure 12. Temperature Coefficients

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PACKAGE DIMENSIONS

SOT-723
CASE 631AA-01
ISSUE C



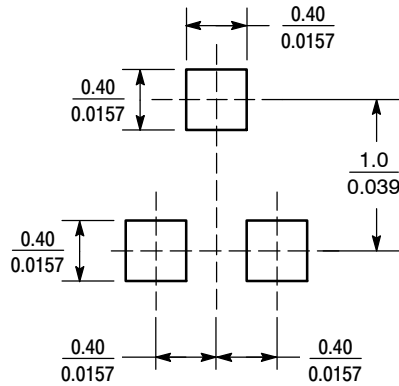
STYLE 1:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
C	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.03	0.032	0.034
e	0.40 BSC			0.016 BSC		
H E	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098

SOLDERING FOOTPRINT*



SCALE 20:1 (mm inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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